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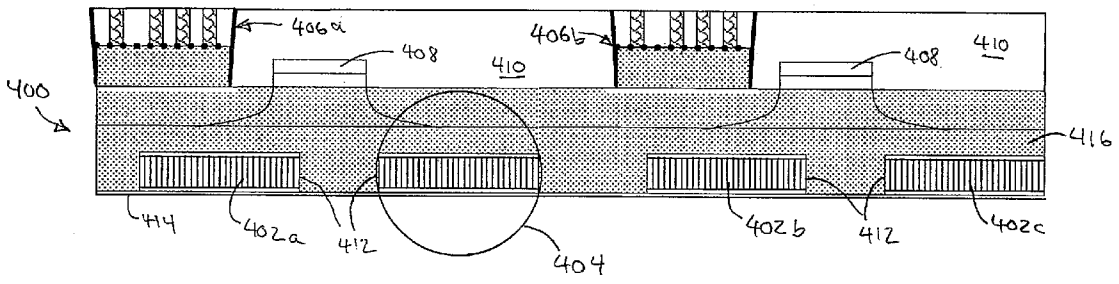
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(54) Title: METHOD AND APPARATUS FOR THE USE OF SELF-ASSEMBLED NANOWIRES FOR THE REMOVAL OF HEAT FROM INTEGRATED CIRCUITS



(57) Abstract: This invention relates to the conduction of heat within the structure of an integrated circuit. The invention discloses a heat conduction device and a method of fabricating same, that utilizes thermally conductive vias to extract heat from local power generating regions of the substrate to top or bottom surfaces of the integrated circuit die. Conductive vias contain self-assembled carbon nanotubes for the enhancement of heat conduction out of the integrated circuit.

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